



Part Number : 787301002

Series Number : 78730

Product Category : Memory Module
Connectors

Product Description : DDR4 DIMM Socket,
Vertical Surface Mount, 0.76µm Gold Plating,
288 Circuits, PCB Thickness 1.57mm, with
Forklock, Black Housing, Black Latch


Status : New Business Not Supported

Engineering Number : 0787301002

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Compliant with Exemption 44; 34; 33
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)8585-DC (23 Jan 2024)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	New Business Not Supported
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Category	Memory Module Connectors
Series	78730
Description	DDR4 DIMM Socket, Vertical Surface Mount, 0.76µm Gold Plating, 288 Circuits, PCB Thickness 1.57mm, with Forklock, Black Housing, Black Latch
Component Type	Socket
JEDEC Outline	MO-309
Product Family	DDR4 DIMM Sockets
Product Name	DDR4 DIMM
UPC	887191429816

Agency

CSA	1409726
UL	E29179

Electrical

Current - Maximum per Contact	0.75A
Voltage - Maximum	29V AC (RMS)/DC

Physical

Circuits (Loaded)	288
Circuits (maximum)	288
Durability (mating cycles max)	25
Entry Angle	Vertical (Top Entry)
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	None
Latch Color	Black
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
Net Weight	6.245/g
Packaging Type	Tray

PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm, 3.18mm
Pitch - Mating Interface	0.85mm
Pitch - Termination Interface	0.85mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Surface Mount

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	REFLOW
Max-Cycle	3
Max-Temp	260